

Full Material Declaration for attached parts list

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Diotec Semiconductor AG

DUNS number: 330866844

-, Kreuzmattenstr. 4, Heitersheim, 79423, Germany

Declarations authorised by:

Udo Steinebrunner, Product Manager, -

Declaration effective from: 15 August 2023 [Approved on 13 March 2026, 12:40 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	2.41%	ALUMINUM, ELEMENTAL	7429-90-5	1.56%
			SILVER, ELEMENTAL	7440-22-4	2.07%
			Silicon	7440-21-3	96.37%
Die attach	Polymeric compounds	4.26%	Diamino-4,4'-diphenyl sulfone	80-08-0	2.5%
			OXIRANE, 2,2'-(1,4-BUTANEDIYLBIS(OXYMETHYLENE))BIS-	2425-79-8	10%
			Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5	17.5%
			SILVER, ELEMENTAL	7440-22-4	70%
Encapsulation	EP (Epoxy resin)	48.8%	Carbon black	1333-86-4	0.9%
			phenolic epoxy resin	61788-97-4	7%
			Epoxy resin 89	26335-32-0	8%
			Quartz sand	60676-86-0	84.1%
Inner preparation	Copper alloys	1.44%	GOLD, ELEMENTAL	7440-57-5	1%
			PALLADIUM, ELEMENTAL	7440-05-3	3%
			SILVER, ELEMENTAL	7440-22-4	96%
Leadfinish	Tin plating	0.55%	Tin elemental	7440-31-5	100%
Leadframe	Copper alloys	42.54%	IRON, ELEMENTAL	7439-89-6	2.6%
			COPPER, ELEMENTAL	7440-50-8	97.4%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOT-23-5_(JA)_Pb-H-free AG	Diode / Transistor SMD	0.01455	g
